7th IEEE Electron Devices Technology and Manufacturing (EDTM) Conference 2023

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8A. Advanced Interposer RDL Technology	
Session Date:	March 8(Wed.), 2023
Session Time:	13:30-14:55
Session Room:	Room A (#301)
Session Chair:	Prof. Bong-Young Yoo (Hanyang University) Dr. Akihiro Horibe (IBM Research Tokyo)

[8A-1] [Invited] **13:30-13:55**

Interposer Trends and Technologies of Heterogeneous Integration

Gu-Sung Kim

Kangnam University

[8A-2] **13:55-14:10**

On-Chip Canary Circuit Design for Electronic Interconnects by Utilizing RF Resonance Peak Movement as a Prognostic Factor

Tae Yeob Kang[1], Donghwan Seo[1] and Taek-Soo Kim[2]

[1]Agency for Defense Development, [2]Korea Advanced Institute of Science and Technology

[8A-3] **14:10-14:25**

Mathematical Optimization Models for Auto Interposer Routing Problem for Improving Signal Integrity

Taewook Kang, Youjung Lee, Joonrak Kim, Joohwan Cho, Sangho Lee, Bumsu Kim, Wontae Kim and Sijeo Park

SK hynix

[8A-4] **14:25-14:40**

Selective Cu Electrodeposition for Through Glass Via (TGV)

Fan Yang, Qing Wang, Jinhyun Lee, Sanghwa Yoon and Bongyoung Yoo

Hanyang University

[8A-5] **14:40-14:55**

Effect of Photo-Definable Dielectric Process Conditions on the Interfacial Reliabilities of Polyimide Capping Layer/ Cu RDL for Fan-Out

Gahui Kim, Doheon Kim and Young-Bae Park

Andong National University